

SURFACE MOUNT FAST RECOVERY RECTIFIER

RS2A THRU RS2M	VOLTAGE RANGE CURRENT	50 to 1000 Volts 1.5 Ampere

FEATURES

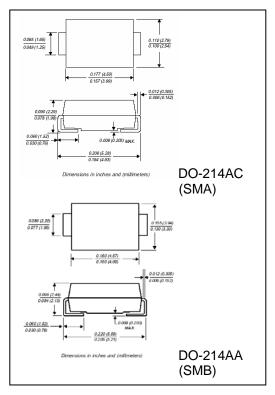
- Glass passivated chip junction
- Built in strain relief
- Fast switching speed for high efficiency
- High temperature soldering guaranteed: $250^{\circ}C / 10$ seconds at terminals
- Also available in the SMA package, add suffix "A", i.e. RS2AA

MECHANICAL DATA

- Case: Transfer molded plastic
- Epoxy: UL 94V-0 rate flame retardant
- Lead: Solder plated, solderable per MIL-STD-750 method 2026
- Polarity: Color band denotes cathode end
- Weight: 0.002 ounce, 0.064 gram DO-214AC (SMA) 0.003 ounce, 0.093 gram – DO-214AA (SMB)

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

- Ratings at 25^oC ambient temperature unless otherwise specified
- Single Phase, half wave, 60Hz, resistive or inductive load
- For capacitive load derate current by 20%



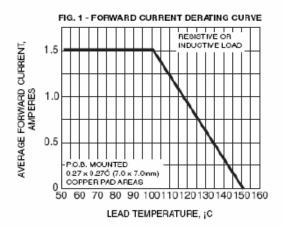
	SYMBOLS	RS2A	RS2B	RS2D	RS2G	RS2J	RS2K	RS2M	UNIT
Maximum Repetitive Peak Reverse Voltage	V _{RRM}	50	100	200	400	600	800	1000	Volts
Maximum RMS Voltage	V _{RMS}	35	70	140	280	420	560	700	Volts
Maximum DC Blocking Voltage	V _{DC}	50	100	200	400	600	800	1000	Volts
Maximum Average Forward Rectified Current, At $T_L = 100^{\circ}C$	I _(AV)	1.5							Amps
Peak Forward Surge Current									
8.3mS single half sine wave superimposed on	I _{FSM}	50							Amps
rated load (JEDEC method)									
Maximum Instantaneous Forward Voltage @ 1.5A	$V_{\rm F}$	1.3							Volts
Maximum DC Reverse Current at Rated $T_A = 25 \ ^{\circ}C$	т	5.0							
DC Blocking Voltage per element $T_A = 125 \ ^{O}C$	I _R	200							μA
Maximum Reverse Recovery Time Test conditions $I_F = 0.5A$, $I_R = 1.0A$, $I_{RR} = 0.25A$	t _{rr}	150 250			250	500		nS	
Typical Junction Capacitance (Measured at 1.0MHz and applied reverse voltage of 4.0V)	C _J	50							pF
Typical Thermal Resistance (Note 1)	$R_{\theta JA}$	105 (SMA) 55 (SMB)							^o C/W
	$R_{\theta JL}$	32 (SMA) 18 (SMB)							
Operating Junction Temperature Range	TJ	(-55 to +150)							°С
Storage Temperature Range	T _{STG}	(-55 to +150)							°С

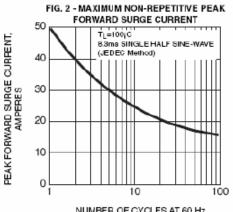
Notes:

 Thermal resistance from junction to ambient and from junction to lead mounted on PCB with 0.27" x 0.27" (7.0mm x 7.0mm) copper pad areas for SMB or 0.2" x 0.2" (5.0mm x 5.0mm) copper pad areas for SMA



RATINGS AND CHARACTERISTIC CURVES RS2A THRU RS2M





NUMBER OF CYCLES AT 60 Hz

FIG. 4 - TYPICAL REVERSE CHARACTERISTICS

